MOSFET – Power, Single N-Channel 60 V, 15.0 mΩ, 36 A

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- NVMFS5C677NLWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	60	٧
Gate-to-Source Voltage	€		V _{GS}	±20	٧
Continuous Drain	Steady State	T _C = 25°C	I _D	36	Α
Current R _{θJC} (Notes 1, 3)		T _C = 100°C		25	
Power Dissipation		T _C = 25°C	P_{D}	37	W
R _{θJC} (Note 1)		T _C = 100°C	1	18	
	Steady State	T _A = 25°C	I _D	11	Α
		T _A = 100°C		7.8	
		T _A = 25°C	P_{D}	3.5	W
		T _A = 100°C		1.8	
Pulsed Drain Current	$T_A = 25^{\circ}C, t_p = 10 \mu s$		I _{DM}	166	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to + 175	°C
Source Current (Body Diode)			I _S	31	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 2.87 A)			E _{AS}	65	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	4.1	°C/W
Junction-to-Ambient - Steady State (Note 2)	R_{\thetaJA}	43	

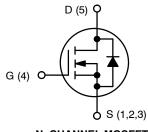
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface–mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



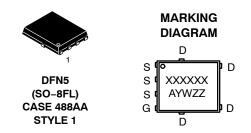
ON Semiconductor®

www.onsemi.com

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX	
60 V	15.0 mΩ @ 10 V	36 A	
00 V	21.5 mΩ @ 4.5 V	30 A	



N-CHANNEL MOSFET



XXXXXX = 5C677L

(NVMFS5C677NL) or

677LWF

(NVMFS5C677NLWF) = Assembly Location

/ = Y

W = Work Week

Z = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS								
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /				26		mV/°C	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	T _J = 25 °C			10	1	
		V _{DS} = 60 V	T _J = 125°C			250	μA 0	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = 20 V				100	nA	
ON CHARACTERISTICS (Note 4)								
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= 25 μΑ	1.2		2.0	V	
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-5.0		mV/°C	
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 10 A		12.5	15.0		
		V _{GS} = 4.5 V	I _D = 10 A		17.9	21.5	mΩ	
Forward Transconductance	9 _{FS}	V _{DS} =15 V, I _D	= 15 A		27.5		S	
CHARGES AND CAPACITANCES								
Input Capacitance	C _{ISS}				620			
Output Capacitance	Coss	V _{GS} = 0 V, f = 1 MHz	z, V _{DS} = 25 V		340		pF	
Reverse Transfer Capacitance	C _{RSS}				7			
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 48 V; I _D = 10 A			4.5		nC	
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 48 V; I _D = 10 A			9.7		nC	
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 10 V, V _{DS} = 48 V; I _D = 10 A			1.3			
Gate-to-Source Charge	Q_{GS}				2.1		nC	
Gate-to-Drain Charge	Q _{GD}				1			
Plateau Voltage	V_{GP}				3.0		V	
SWITCHING CHARACTERISTICS (Note 5	5)							
Turn-On Delay Time	t _{d(ON)}				7			
Rise Time	t _r	V _{GS} = 10 V, V _{DS}	s = 48 V,		13		1	
Turn-Off Delay Time	t _{d(OFF)}	$I_D = 10 \text{ A}, R_G = 1 \Omega$			25		ns	
Fall Time	t _f				6			
DRAIN-SOURCE DIODE CHARACTERIS	TICS						•	
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V, I _S = 10 A	T _J = 25°C		0.85	1.2		
			T _J = 125°C		0.72			
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, dIs/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 10 \text{ A}$			23.8			
Charge Time	ta				11.9		ns	
Discharge Time	t _b				11.8			
Reverse Recovery Charge	Q _{RR}				11.6		nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$.

5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

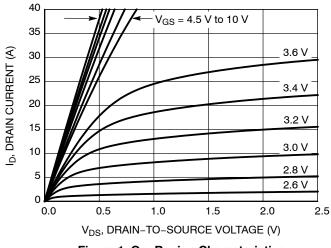


Figure 1. On-Region Characteristics

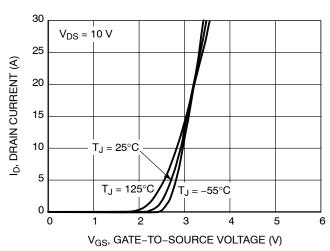


Figure 2. Transfer Characteristics

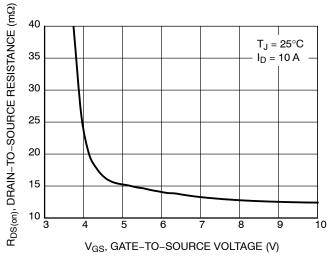


Figure 3. On-Resistance vs. Gate-to-Source Voltage

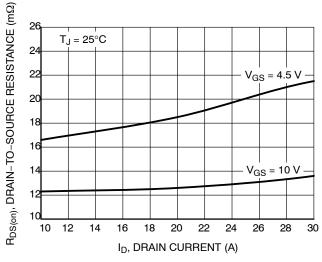


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

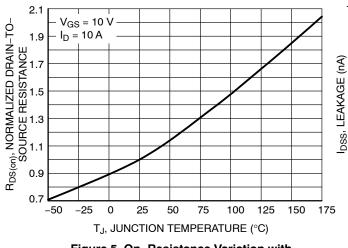


Figure 5. On–Resistance Variation with Temperature

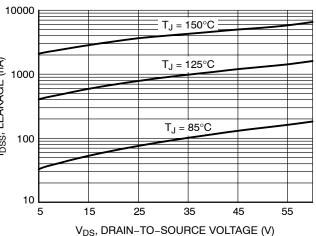


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

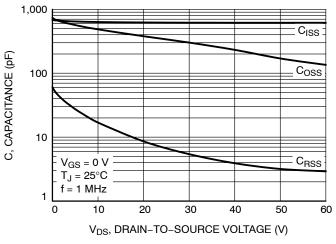


Figure 7. Capacitance Variation

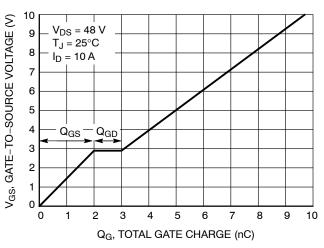


Figure 8. Gate-to-Source vs. Total Charge

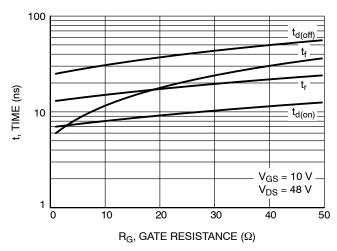


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

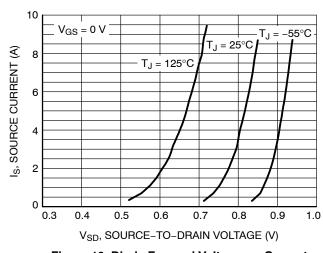


Figure 10. Diode Forward Voltage vs. Current

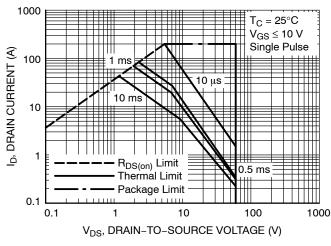


Figure 11. Maximum Rated Forward Biased Safe Operating Area

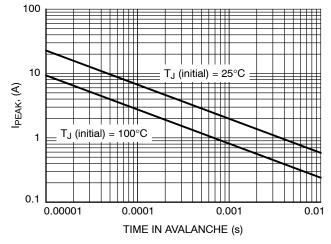


Figure 12. I_{PEAK} vs. Time in Avalanche

TYPICAL CHARACTERISTICS

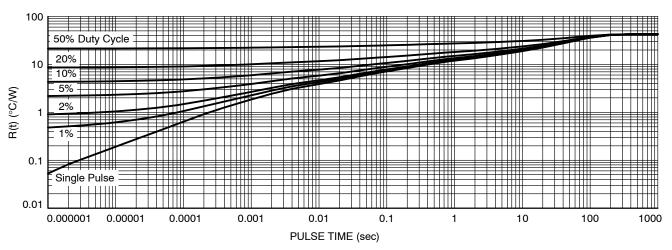


Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NVMFS5C677NLT1G	5C677L	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5C677NLWFT1G	677LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





0.10

SIDE VIEW

DFN5 5x6, 1.27P (SO-8FL) CASE 488AA ISSUE N

DATE 25 JUN 2018

NOTES:

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETER. DIMENSION D1 AND E1 DO NOT INCLUDE
- MOLD FLASH PROTRUSIONS OR GATE BURRS

	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	0.90	1.00	1.10		
A1	0.00		0.05		
b	0.33	0.41	0.51		
С	0.23	0.28	0.33		
D	5.00	5.15	5.30		
D1	4.70	4.90	5.10		
D2	3.80	4.00	4.20		
E	6.00	6.15	6.30		
E1	5.70	5.90	6.10		
E2	3.45	3.65	3.85		
е		1.27 BSC			
G	0.51	0.575	0.71		
K	1.20	1.35	1.50		
L	0.51	0.575	0.71		
L1	0.125 REF				
M	3.00	3.40	3.80		
θ	0 °		12 °		

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code

= Lot Traceability

= Assembly Location Α

Υ = Year W = Work Week

ZZ

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.





DETAIL A

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Electronic versions are uncontrolled except when accessed directly from the Document Repository. **DOCUMENT NUMBER:** 98AON14036D Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. **DESCRIPTION:** DFN5 5x6, 1.27P (SO-8FL) **PAGE 1 OF 1**

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales